

UiO : **Department of Informatics**
University of Oslo

IN4180 - Analog Microelectronics Design

Advanced MOSFET modelling, passives and EDA tools

Kristian G. Kjelgård



Topics

Body effect

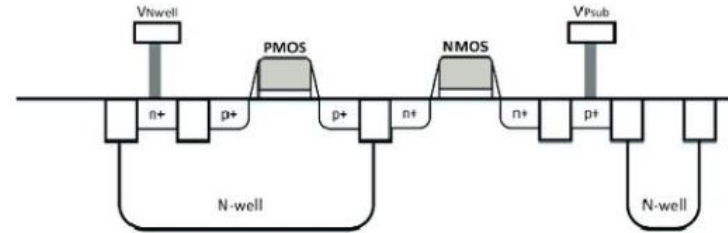
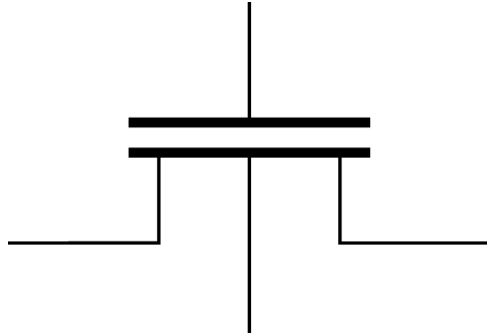
Short channel effects

- Mobility Degradation
- Drain Induced Barrier Lowering
- Hot carriers

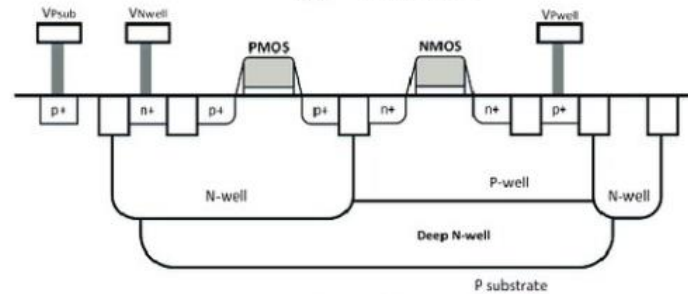
Passives

EDA tools

The 4th terminal



(a) Dual-well



(b) Triple-well

Body effect

- Back-gate effect, substrate effect
- Current change as V_{SB} is different from zero
- Modeled as change in threshold voltage

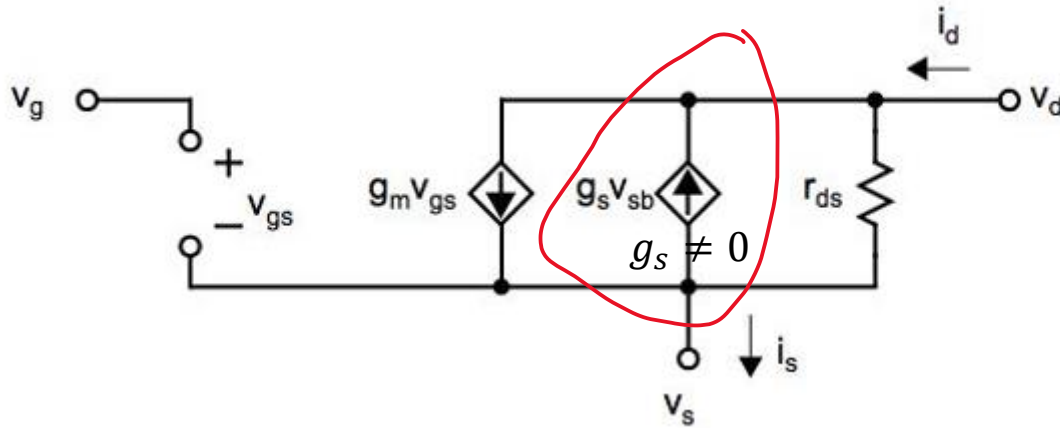
$$V_{tn} = V_{tn0} + \gamma \left(\sqrt{V_{SB} + |2\phi_F|} - \sqrt{|2\phi_F|} \right)$$

- V_{tn0} – zero biased threshold voltage

$$\gamma = \sqrt{\frac{2qN_A K_S \epsilon_0}{C_{ox}}}$$

ϕ_F - Fermi potential

Body effect – small signal



$$g_s = \frac{\partial I_D}{\partial V_{SB}} = \frac{\partial I_D}{\partial V_{tn}} \frac{\partial V_{tn}}{\partial V_{SB}} = \frac{\gamma g_m}{2\sqrt{V_{SB} + |2\phi_F|}}$$

- If bulk connected to source

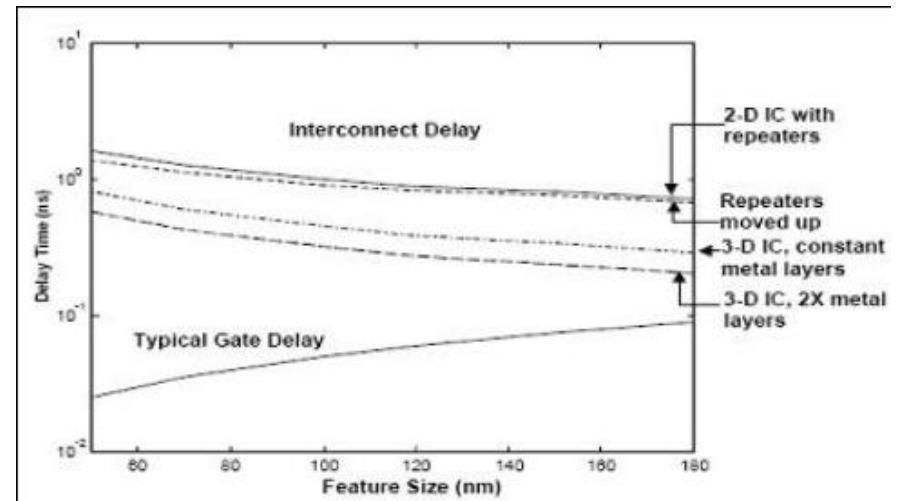
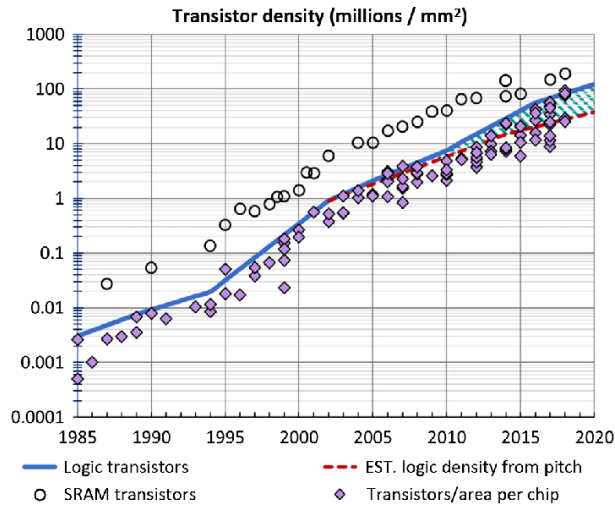
$$g_s = 0$$

- If $V_{sb} \neq 0$

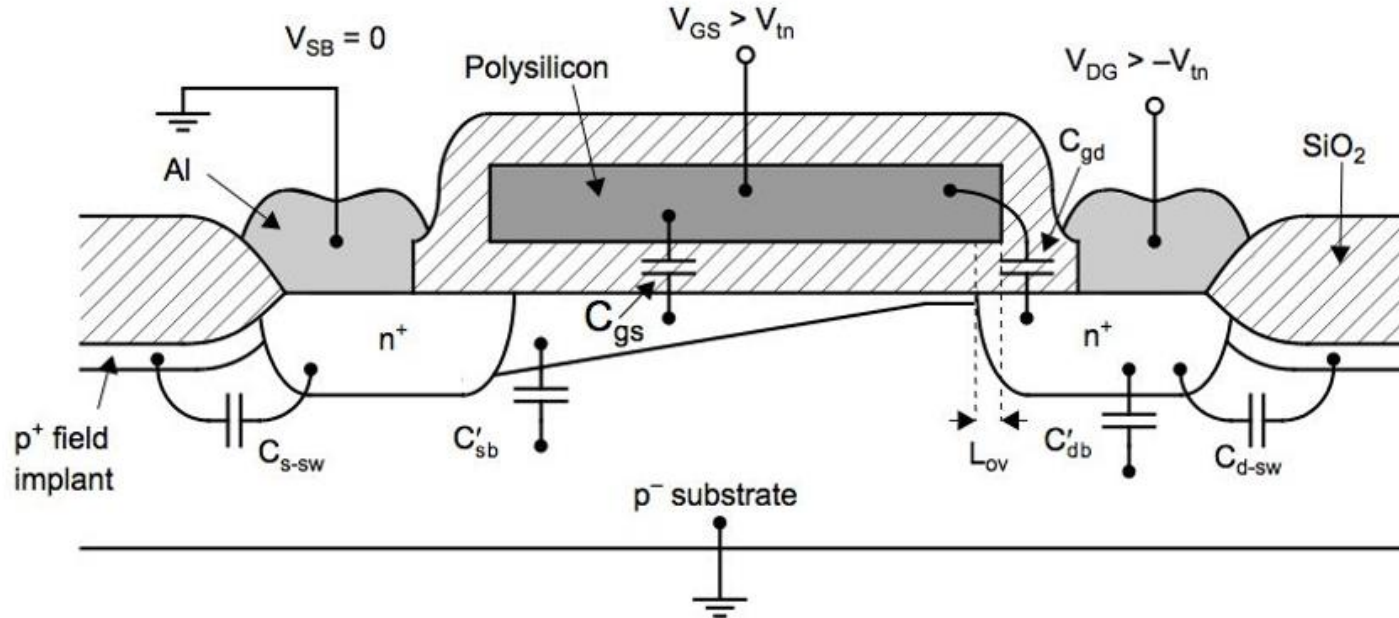
$$g_s \neq 0$$

Why scaling?

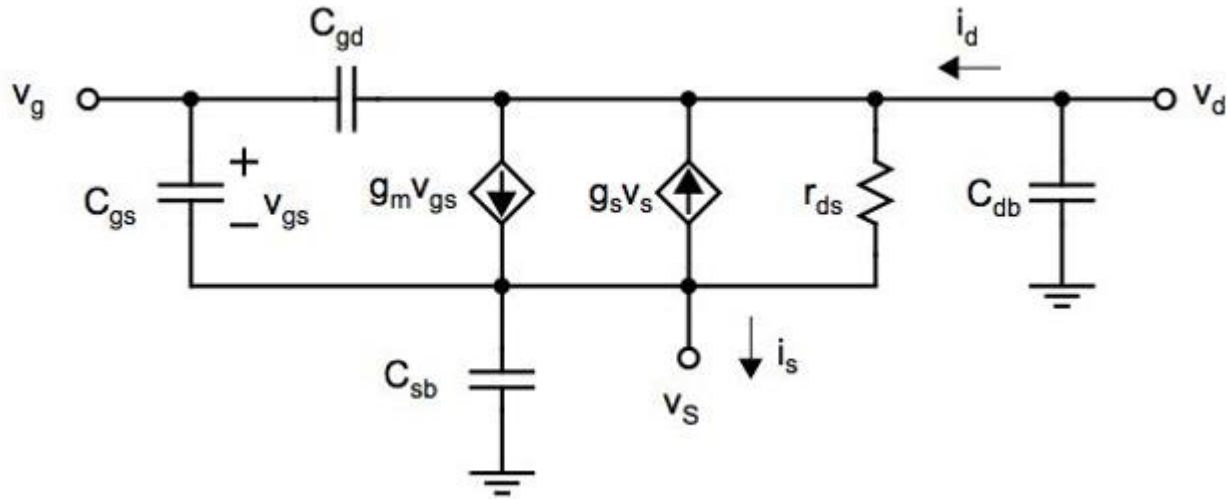
- Transistor density
- Speed



X-section with capacitance

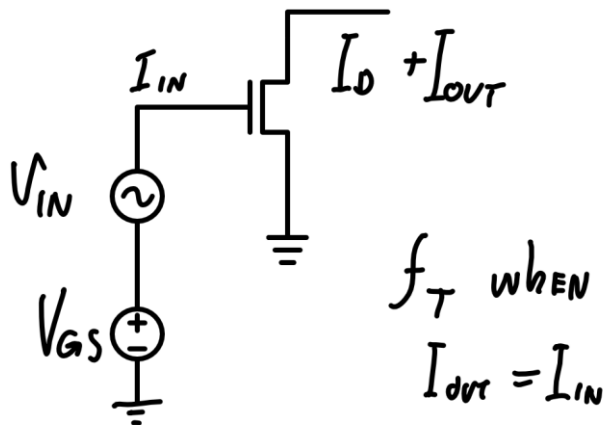


Small signal model with capacitances

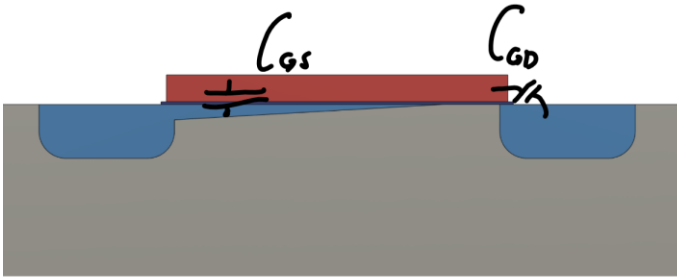


f_T transition frequency - transistor speed

- Higher f_T -> faster digital systems and analog/RF (ie mmwave radio / radar systems)



Current gain unity gain frequency



$$f_T \approx \frac{g_m}{2\pi(C_{GS} + C_{GD})}$$

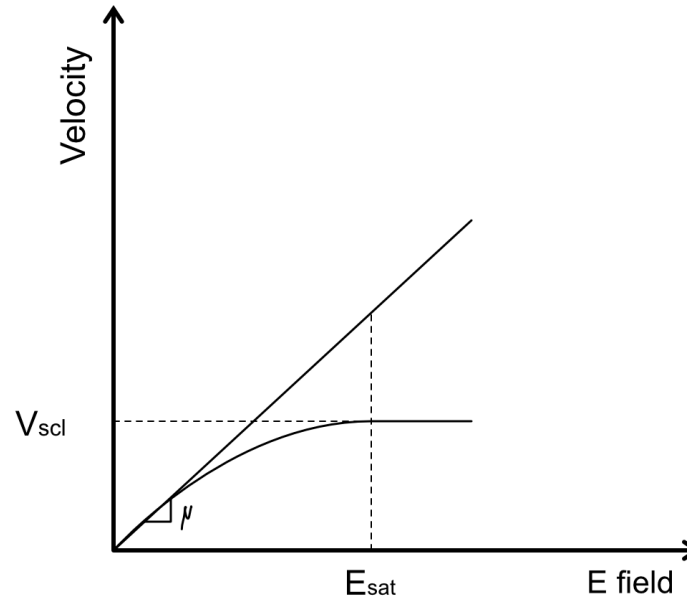
Assumes μ_n constant...

$$f_T \approx \frac{\mu_n C_{OX} \left(\frac{W}{L}\right) V_{EFF}}{2\pi C_{OX} W \left(\frac{2}{2}\right) L} = \frac{3 \mu_n V_{EFF}}{4\pi L^2}$$

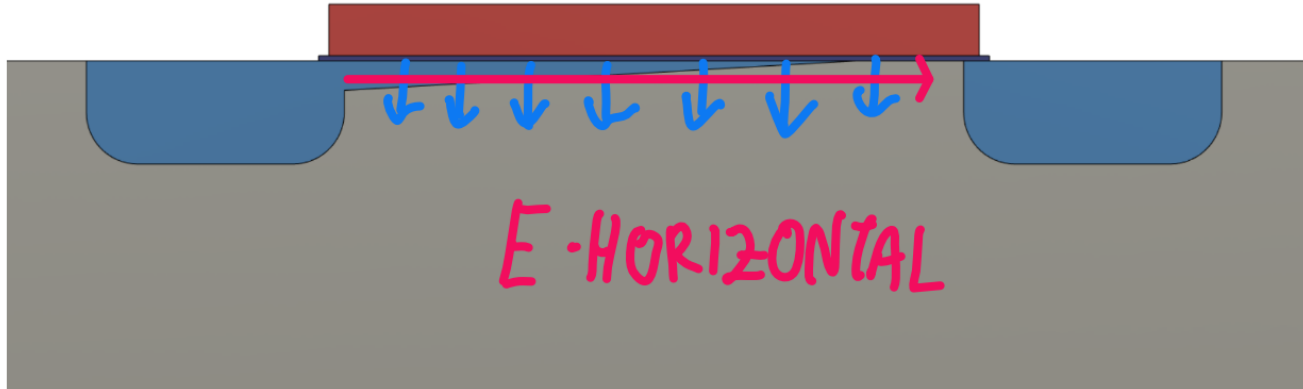
- Lower capacitance and higher G_m with shorter L
- f_T proportional to $1/L^2$

Mobility degradation - μ_n with high E

- When transistors scale E gets high and mobility degraded
- Velocity of charge carrier limited to 10^7 cm/s
- Affects speed and transconductance



E -VERTICAL



$$n_{eff} = \frac{n_n}{(1 + (\theta V_{EFF})^m)^{1/m}}$$

$$V_{EFF} \gg 1/\theta$$

↓ MOBILITY
DEGRADATION
TERM

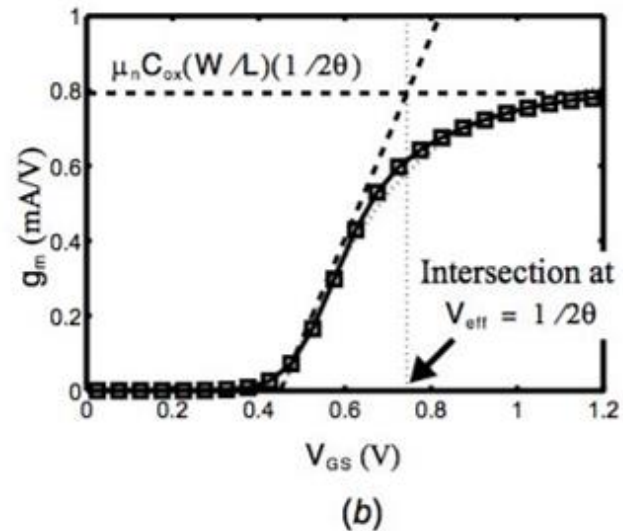
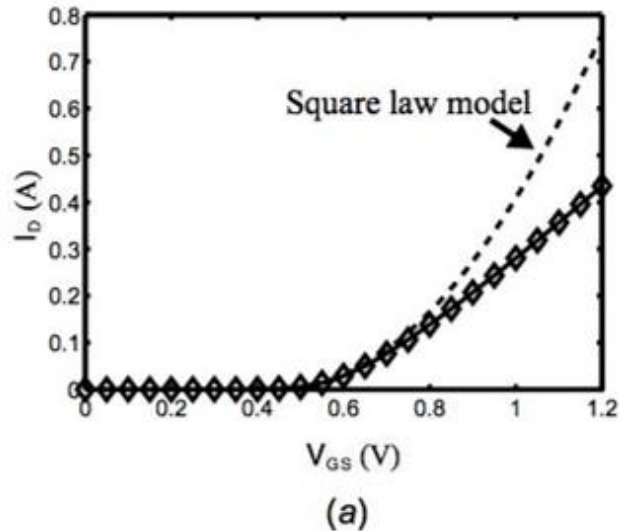
$$1/\theta V_{EFF}$$

↓ SQUARE
LAW

$$I_D = \frac{1}{2} n_n C_{OX} \frac{W}{L} \frac{V_{EFF}^2}{\theta V_{EFF}}$$

High V_{eff} -> less control of channel
Square law -> linear

Implications



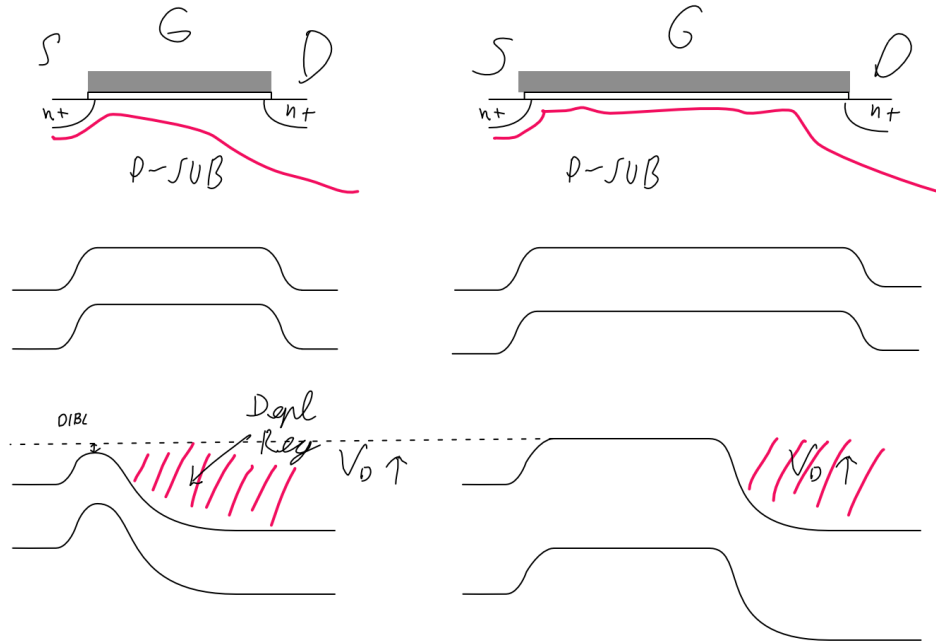
- Small-signal transconductance limited
- Reduced available signal swing
- Reduction in intrinsic gain A_i

Example

- 1.25 Make a qualitative sketch of transistor intrinsic gain A_i versus V_{eff} for:
- Constant device width W

In each case what is the relationship between A_i and V_{eff} in weak-inversion, active mode and under mobility degradation

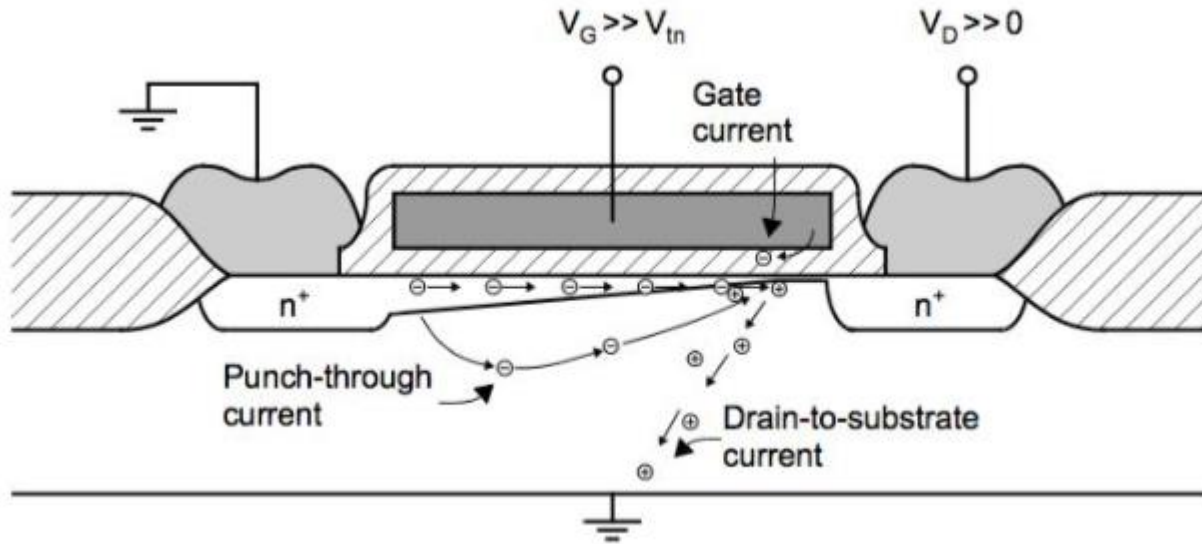
Drain Induced Barrier Lowering (DIBL)



Drain Induced Barrier Lowering (DIBL)

- V_t dependence on V_{ds}
- Current dependent on V_{ds} -> reduced r_{ds}

Hot carriers



High velocity carriers

- E-H pairs -> Drain-to-substrate current
- Gate oxide tunnel
- Electrons in oxide trapped

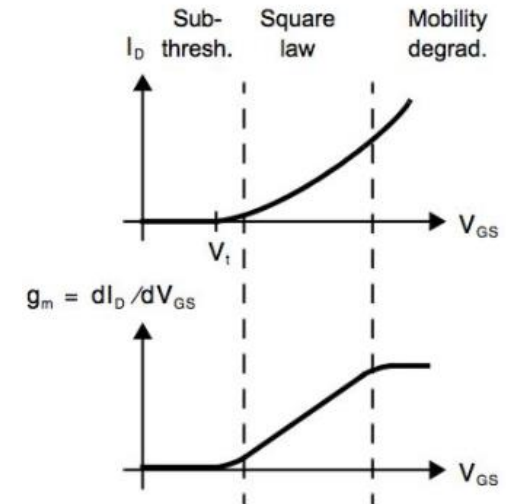
Leakage Current

- Gate -> channel quantum-mechanical tunnel
- pn reverse junction leakage

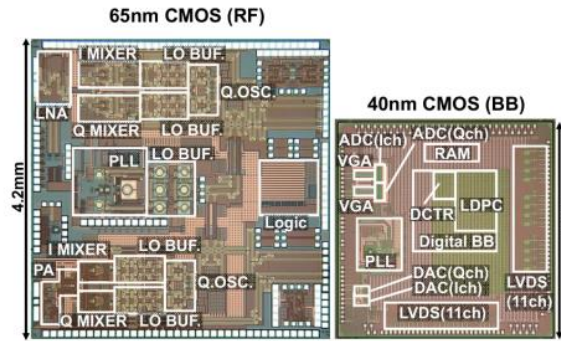
$$I_{IK} = \frac{q A n_i x_d}{2 \tau_0}$$

Summary

- In modern CMOS technology a large variety of effects gives a non-ideal transistor behaviour
- Basic models used for "intuition" and design ideas
- Non-ideal characteristics very significant
- When to use simulator?

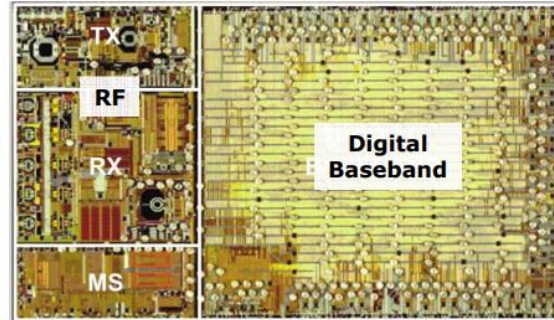


SoC integration planar mosfet technology



A. Matsuzawa, IEDM (2012)

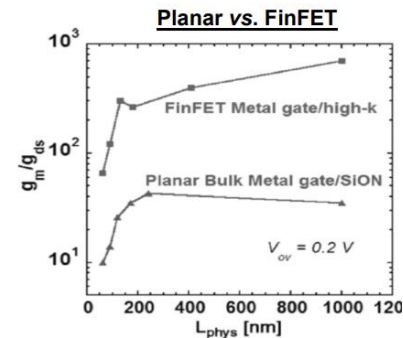
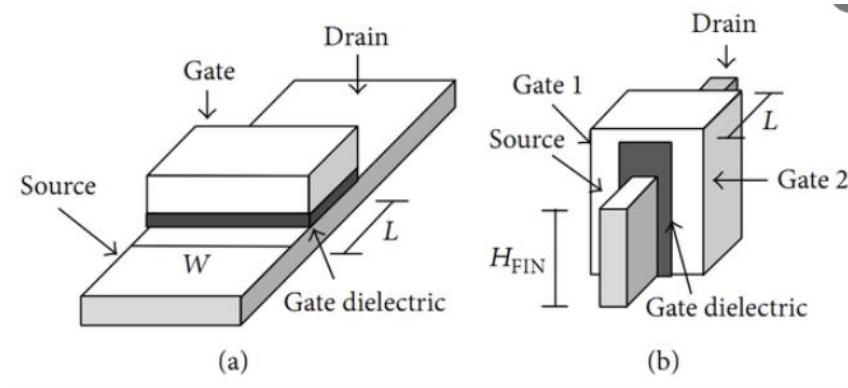
65nm SoC (Qualcomm)



A. Cicalini, ISSCC (2011)

Sub 40 nm technologies -> finfet

- Next generation analog / Radio Frequency SoC in finfet technology?

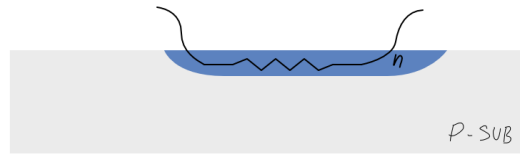


P. Wambacq, TCS (2007)

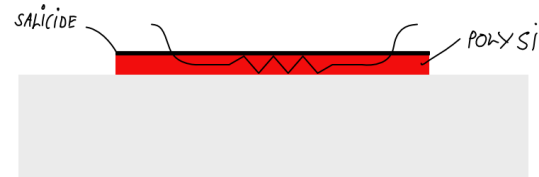
CMOS passives

Resistors in CMOS

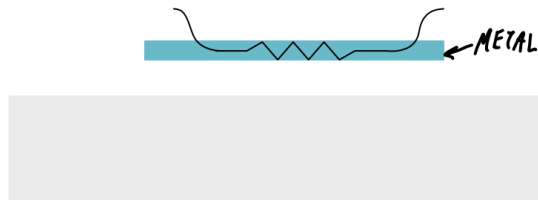
Diffusion



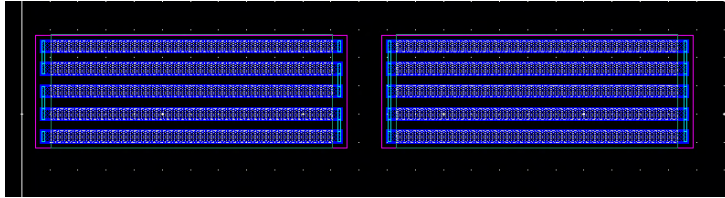
Polysilicon



Metal



Meandering / layout of resistors



Cadence Instances

Diffusion:
rpd
rpdwo

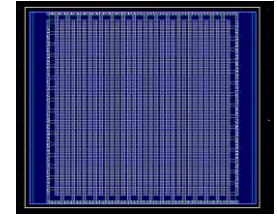
rnod
rnodwo

Poly:
rnpoly
rnpolywo

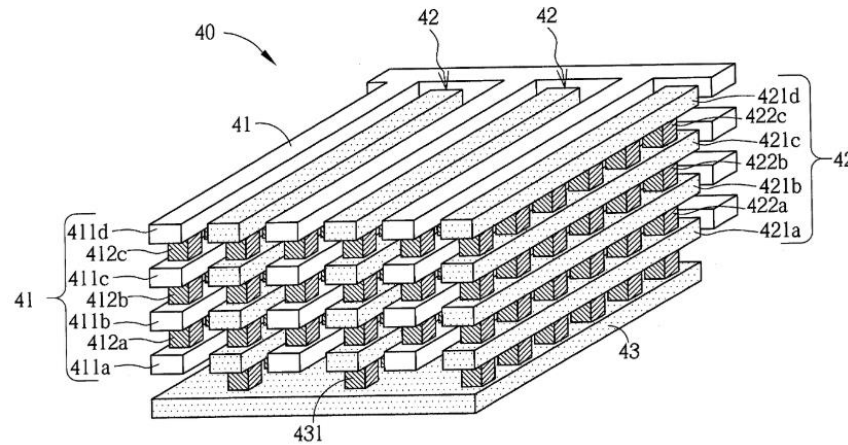
Metal:
rmN (n=metal layer)

Wo = without silicide
-> higher resistance

Cadence
crtmom



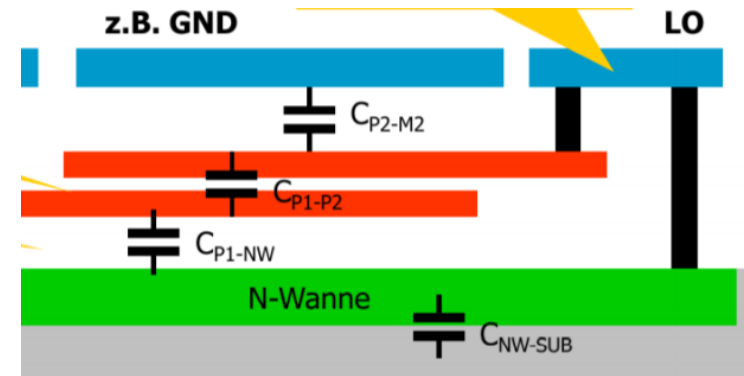
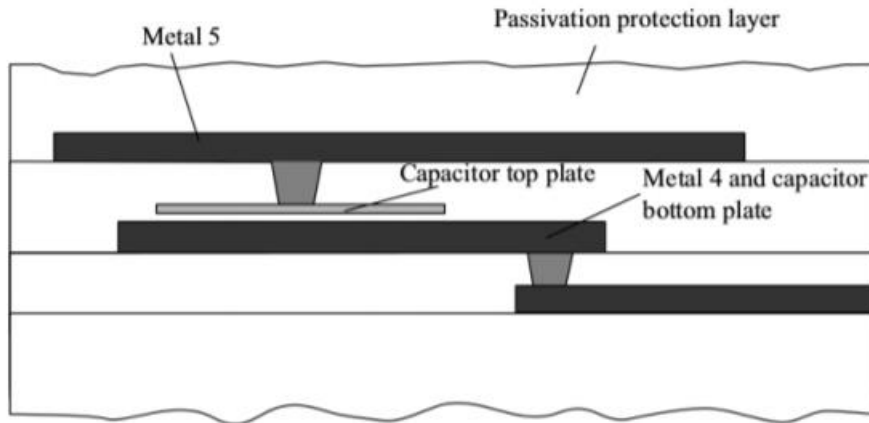
MOMCAP



Use the standar BOEL (back end of line) metal layers and Silicon Oxide to form capacitor.

In modern process high density (fF/um³) can be achieved

MIMCAP



Extra high permittivity layer between $Met_{(n)}$ and $Met_{(n-1)}$
Added cost to production with extra steps
Sensitive to antenna errors

MOSCAP

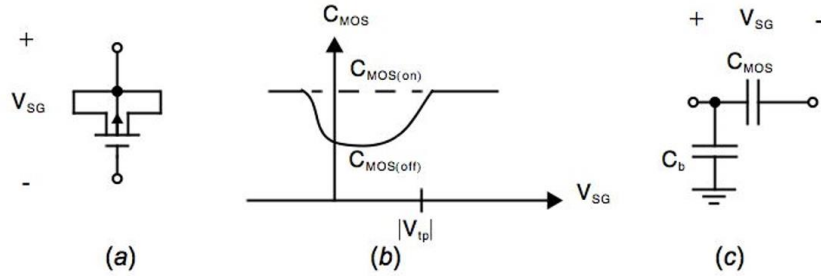
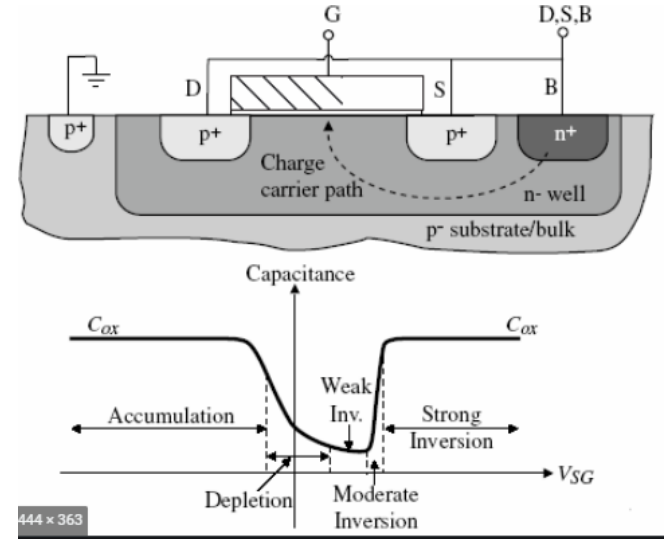
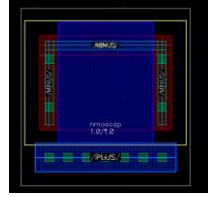


Fig. 1.36 A PMOS capacitor: (a) schematic symbol; (b) nonlinear capacitance; (c) small-signal model.

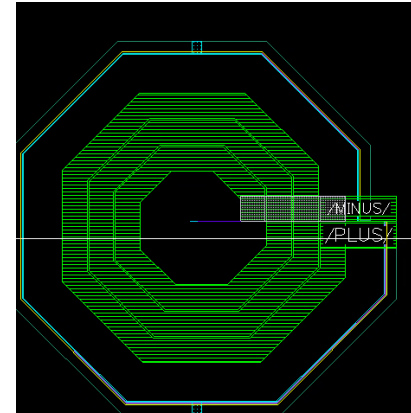
- Use transistor gate oxide for capacitor
- Capacitance dependent on voltage
- High C- bulk

Cadence
nmoscap



Inductors

- Spiral inductors with and without centre tap
- On chip inductors mainly used for RF applications
- Doping under inductor coil is critical due to eddy currents loss. -> low Q



Passives summary

Different implantations of passives.

Trade-off between area, quality, cost

IC process is stochastic -> random variation in values

Layout of passives critical for high precision values.,

EDA – Electronic Design Automation

- Modelling of the MOSFET is very complex and too much to consider for analytic expressions and hand calculations
- Numerical computational methods
- Berkeley Short-channel IGFET Model - BSIM widely used developed at Berkeley


```

* PTM High Performance 45nm Metal Gate / High-K / Strained-Si
* nominal Vdd = 1.0V

.model nmos nmos level = 54

+version = 4.0          binunit = 1          paramchk= 1          mboomod = 0
+capmod = 2            igcmmod = 1          igbmod = 1           geomod = 1
+diomod = 1           rdsmod = 0           rtbodymod = 1        rgatemod= 1
+permod = 1           acnqsmod= 0          trnqsmod= 0

+tnom = 27            toxex = 1.25e-009      toxp = 1e-009        toxm = 1.25e-009
+dtox = 2.5e-010     epsrox = 3.9          wint = 5e-009        lint = 3.75e-009
+l1 = 0               w1 = 0               l1n = 1              w1n = 1
+lw = 0               vw = 0               lwn = 1              wvn = 1
+lwl = 0              vwl = 0              xpart = 0            toxref = 1.25e-009
+xl = -20e-9

+vth0 = 0.46893      k1 = 0.4              k2 = 0               k3 = 0
+k3b = 0              w0 = 2.5e-006        dvt0 = 1             dvt1 = 2
+dvt2 = 0             dvt0w = 0            dvt1w = 0            dvt2w = 0
+dsusb = 0.1         minv = 0.05          voff1 = 0            dvtp0 = 1e-010
+dvtp1 = 0.1         lpe0 = 0             lpeb = 0             xj = 1.4e-008
+ngate = 1e+023      ndep = 3.24e+018     nsd = 2e+020         phin = 0
+cdsc = 0            rfdscb = 0           cdsdc = 0            cit = 0
+voff = -0.13        rfactor = 2.22        eta0 = 0.0055        etab = 0
+vfb = -0.55         u0 = 0.054           ua = 5e-010          ub = 1.2e-018
+uc = 0              vsat = 170000        a0 = 1               ags = 0
+a1 = 0               a2 = 1               b0 = 0               bl = 0
+keta = 0.04         dvg = 0              dwb = 0              pclm = 0.02
+pdiblc1 = 0.001     pdiblc2 = 0.001      pdiblc3 = -0.005     dnout = 0.5
+pvag = 1e-020       delta = 0.01          psbbe1 = 8.14e+008   psbbe2 = 1e-007
+fprout = 0.2        pdits = 0.08          pditsd = 0.23        pdits1 = 2300000
+rsh = 5             rds = 155            rsw = 80             rdw = 80
+rdswmin = 0         rdummin = 0          rswmin = 0           prwg = 0
+prwb = 0            wr = 1               alpha0 = 0.074       alpha1 = 0.005
+beta0 = 30          agl01 = 0.0002       bgl01 = 2.1e+009     cgl01 = 0.0002
+egidl = 0.8         agbacc = 0.012        bigbacc = 0.0028     cgbacc = 0.002
+nigbacc = 1         aigbinv = 0.014       bigbinv = 0.004      cigbinv = 0.004
+eigbinv = 1.1       nigbinv = 3           aigc = 0.02          bigc = 0.0025
+cigc = 0.002        aigsd = 0.02         bigsd = 0.0025       cigsd = 0.002
+nigc = 1            poxedge = 1          pigcd = 1            ntoc = 1
+xrcrg1 = 12         xrcrg2 = 5

+cgso = 1.1e-010     cgdo = 1.1e-010      cgbo = 2.56e-011     cgd1 = 2.653e-010
+cgsl = 2.653e-010  ckappas = 0.03        ckappad = 0.03       acde = 1
+moin = 15          noff = 0.9           voffcv = 0.02

+kt1 = -0.11         kt11 = 0              kt2 = 0.022          ute = -1.5
+u01 = 4.31e-009    ub1 = 7.61e-018       uc1 = -5.6e-011      prt = 0
+at = 33000

+fnoimod = 1         tnoimod = 0

+jss = 0.0001        jsws = 1e-011         jswgs = 1e-010       njs = 1
+ijthsfwd = 0.01     ijthsrev = 0.001      bvs = 10             xjbvs = 1
+jsd = 0.0001        jswd = 1e-011         jswgd = 1e-010       njd = 1
+ijthdfwd = 0.01     ijthdrev = 0.001      bvd = 10             xjbvd = 1
+pbs = 1             cjs = 0.0005          mjs = 0.5            pbsus = 1
+cjsws = 5e-010      mjsws = 0.33          pbswgs = 1           cjswgs = 3e-010
+mjswgs = 0.33       pbd = 1               cjd = 0.0005         mjd = 0.5
+pbsvd = 1           cjsvd = 5e-010        mjsvd = 0.33         pbsvgd = 1
+cjswgd = 5e-010     mjsvgd = 0.33        tpb = 0.005          tcj = 0.001
+tpbsv = 0.005       tcjsw = 0.001         tpbsvg = 0.005       tcjswg = 0.001
+xtis = 3           xtld = 3

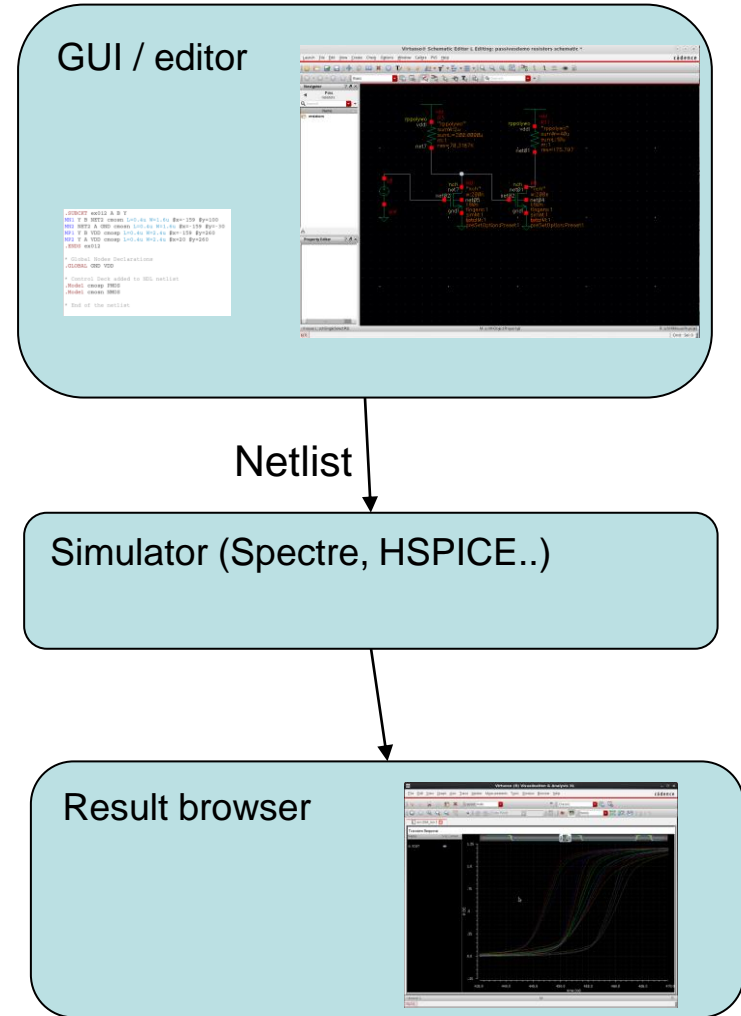
+dmcg = 0            dmci = 0              dmdg = 0             dmcgt = 0
+dwj = 0             xgv = 0              xgl = 0

+rshg = 0.4          gbmim = 1e-010       rbpb = 5              rbpd = 15
+rbps = 15          rbdb = 15            rbsb = 15            ngcon = 1

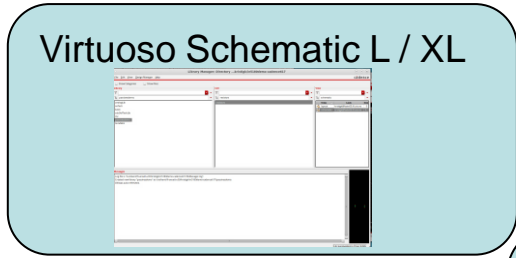
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Circuit simulation

- Spectre – Cadence
- HSPICE – synopsis
- UltraSIM

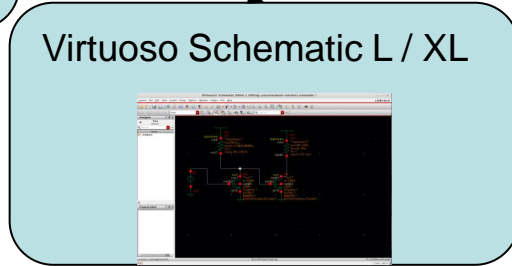


IN5180 – Tool flow schematic simulation



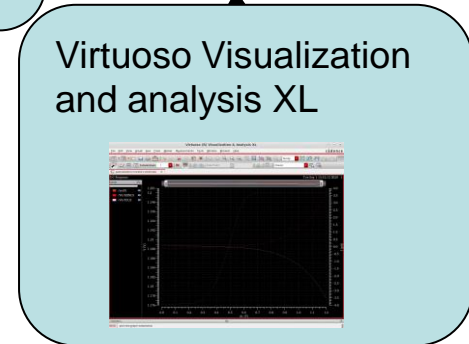
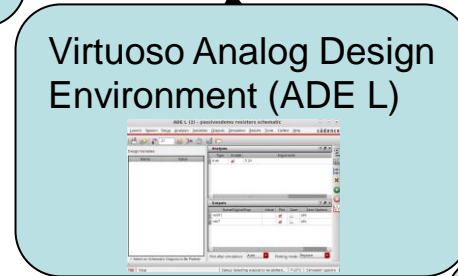
Hierarchy and
library organization

Library -> cell ->
cellview



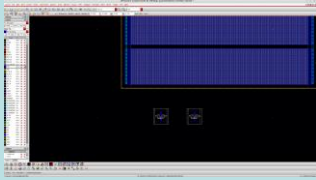
Schematic/symbol
cellview

ADE GXL can make
adexl cellview for
organizing
simulations (not
needed for ADE L)



IN5180 – Tool flow layout and DRC

Virtuoso Layout L / XL



Layout cellview

Draw layout /
generate from
schematic

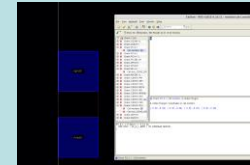
Mentor Calibre nmDRC



Check layout for
errors (spacing,
widths area etc..)

Locate errors in
layout and fix

Mentor Calibre RVE



IN5180 – post layout extraction flow

